

Announcement and Call for Abstracts

IMAPS and SEMI Proudly announce a Joint Topical Workshop on **Adhesives/Encapsulants/Molding**

www.imaps.org/aem

*This event will run parallel to the Wire Bonding workshop
with one admission fee prior to SEMICON West 2009 – July 14-16.*

July 13, 2009

Moscone Center

San Francisco, California - USA

Abstract Deadline Extended: February 20, 2009

General Chair:	Wire Bonding Workshop Organizing Committee:		
Steve Adamson Asymtek Carlsbad, CA 92606 P: 760-930-7274 sadamson@asymtek.com	Dave Gibson	Henkel	dave.gibson@us.henkel.com
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Adhesives/Encapsulants/Molding Workshop Focus:

The objective of the Adhesives, Encapsulation and Molding Workshop is to have a unique forum that brings together scientists, engineers, manufacturing, academia, and business people who have been working in this area of technology. This workshop has been specifically organized to allow for the presentation on the latest current thinking on these focus areas of technologies.

- Glob Top Encapsulants
- Thermo-Compression Molded Packages
- Corner and Edge Bond of CSP Devices
- CSP Underfill
- Flip Chip Underfill
- Flip Chip Underfill and Molding
- Surface Preparation to Improve Adhesion and Flow Characteristics
- Simulation and Modeling
- Failure Analysis and Reliability
- UV Adhesives
- Alternative Interconnect for Flip Chip

Those wishing to present a paper at the Adhesives, Encapsulation and Molding Topical Workshop must submit a 200-300 word abstract electronically **no later than February 20, 2009**, using the on-line submittal form at: www.imaps.org/abstracts.htm. Full written papers are not required; however, an extended abstract of 1-4 pages is due for accepted presenters no later than June 12, 2009.

Please contact Jackki Morris-Joyner by email at jmorris@imaps.org or by phone at 202-548-4001 if you have questions.

Accepted papers may be considered for publication in the IMAPS *Journal of Microelectronics and Electronic Packaging*. **All Speakers are required to pay a reduced registration fee and are required to attend the entire event.**

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